

EGE535 Low Power VLSI Design

Lecture #2

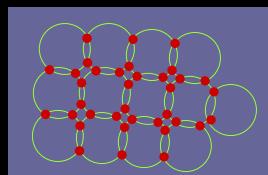
MOSFET Basics

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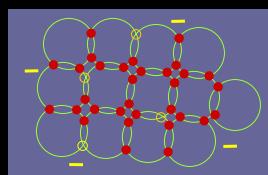
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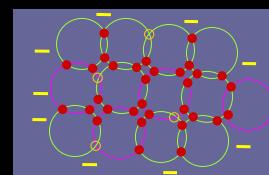
Intrinsic and extrinsic Semiconductors



Intrinsic semiconductor
(no carriers at 0°K)



Intrinsic semiconductor
($n_i = p_i$ at room temp)



N type semiconductor
($n_i \gg p_i$ at room temp)



N type semiconductor
($n_i \gg p_i$ at room temp)

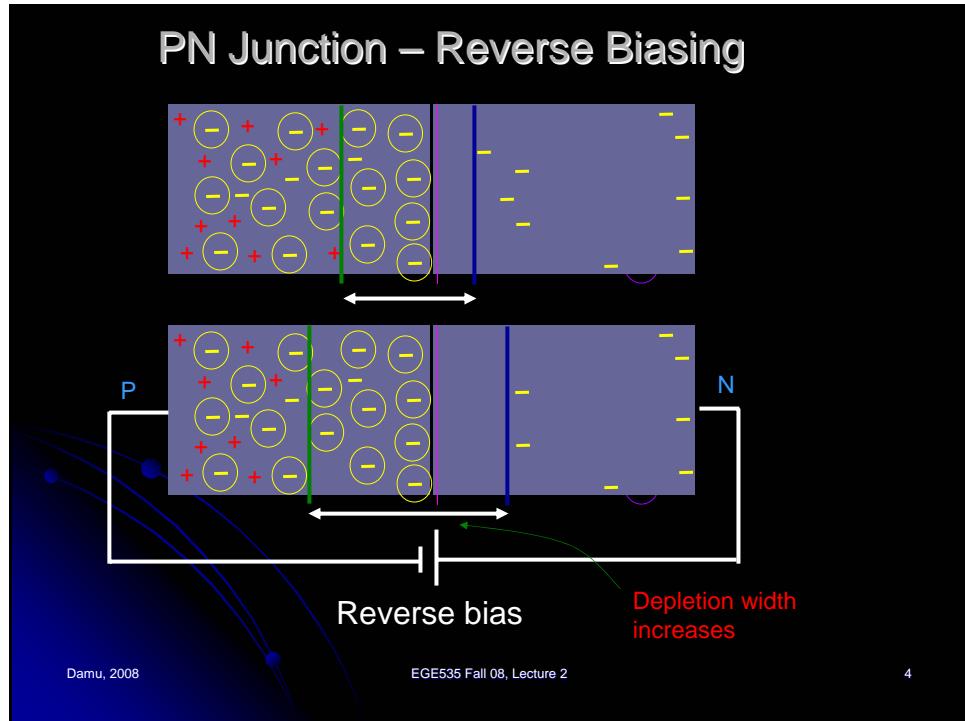
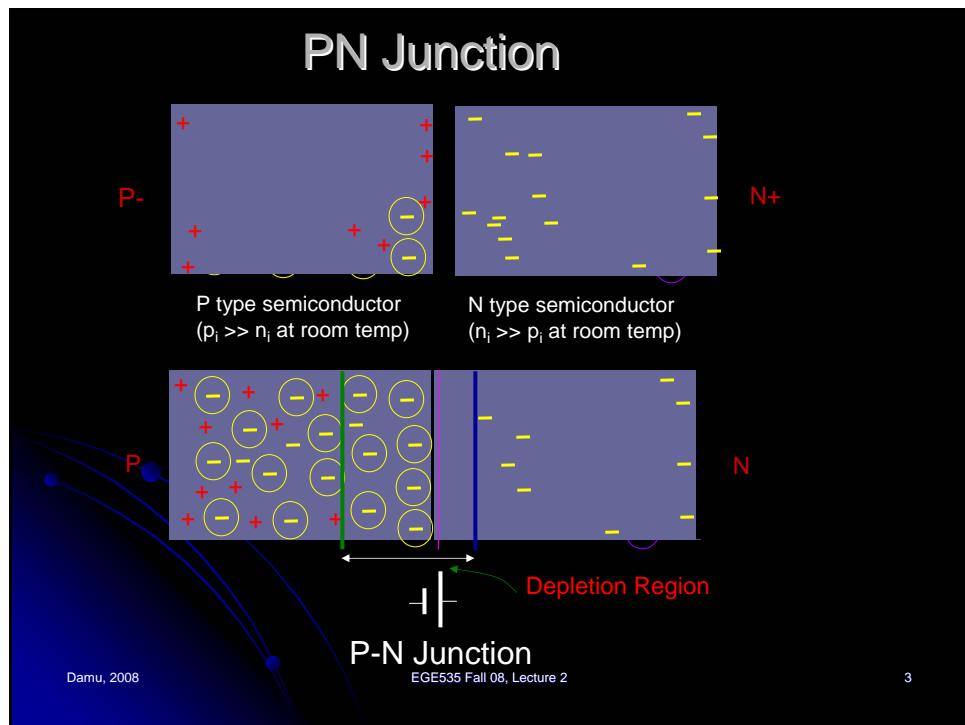


P type semiconductor
($p_i \gg n_i$ at room temp)

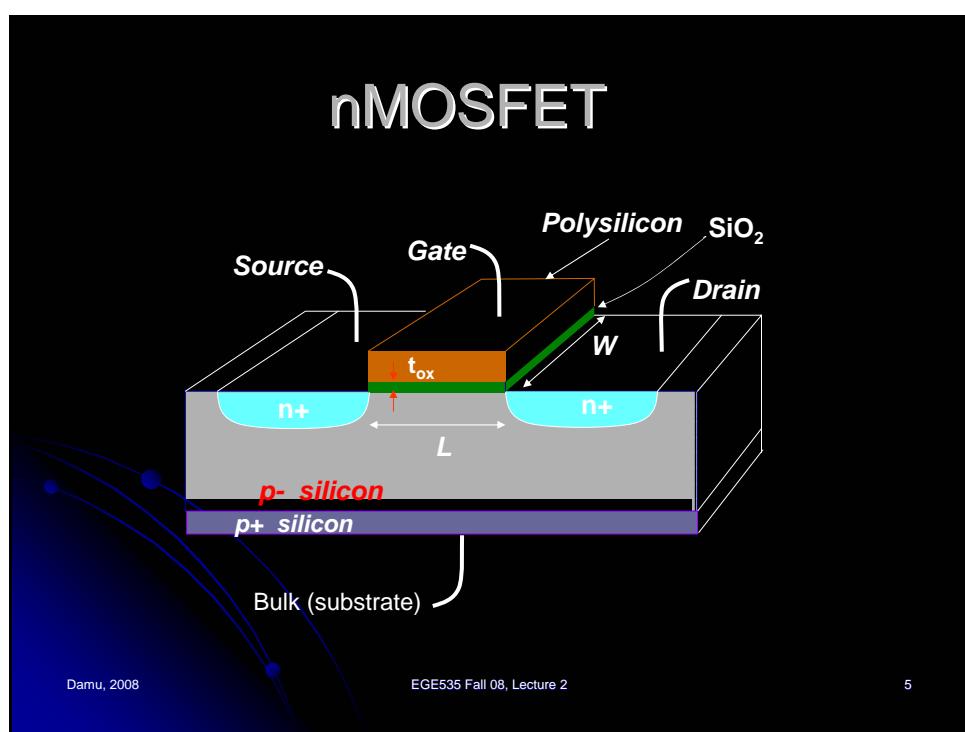
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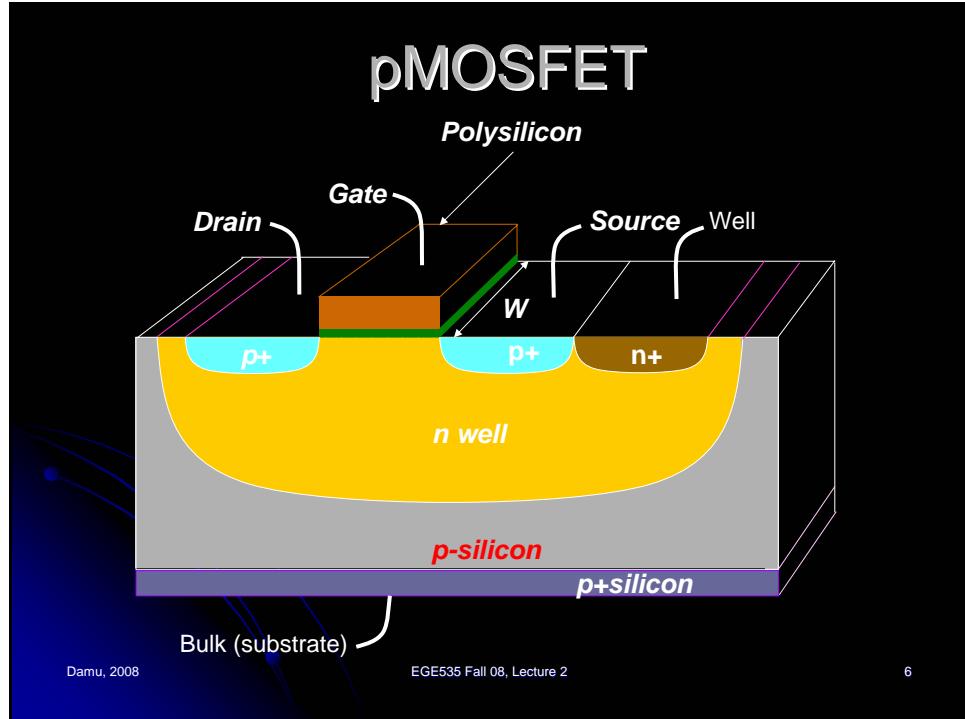
2



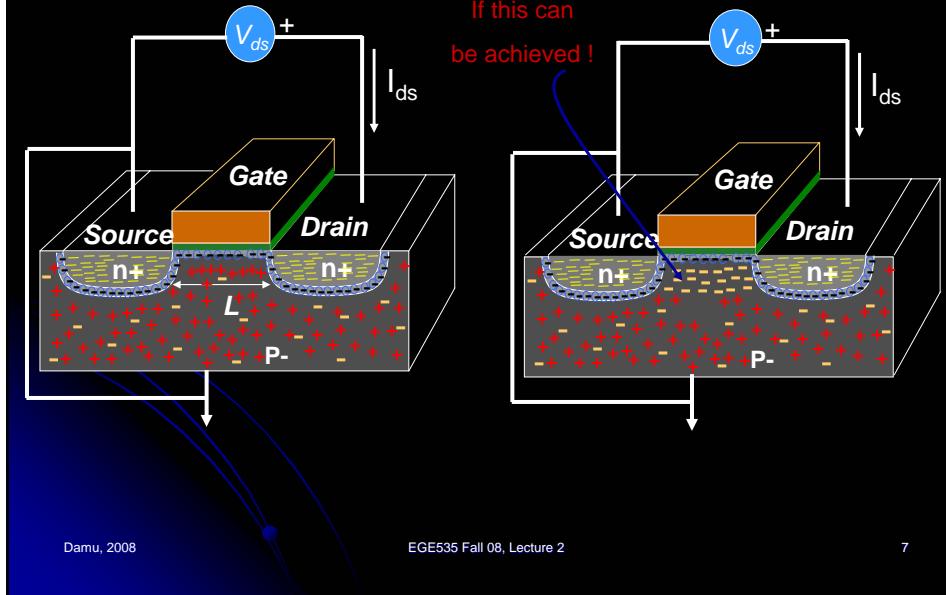
nMOSFET



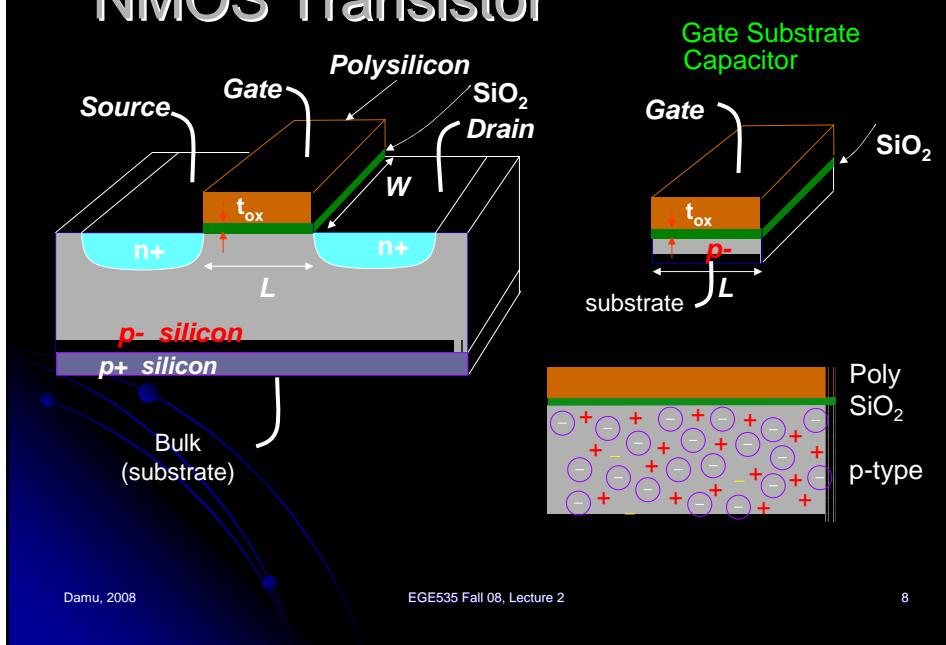
pMOSFET



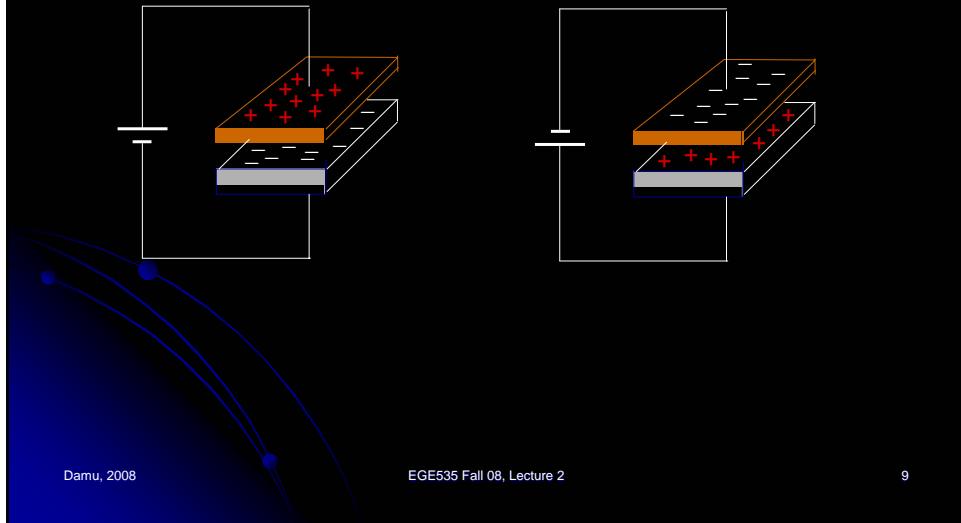
Objective: to have current flow between Source and Drain



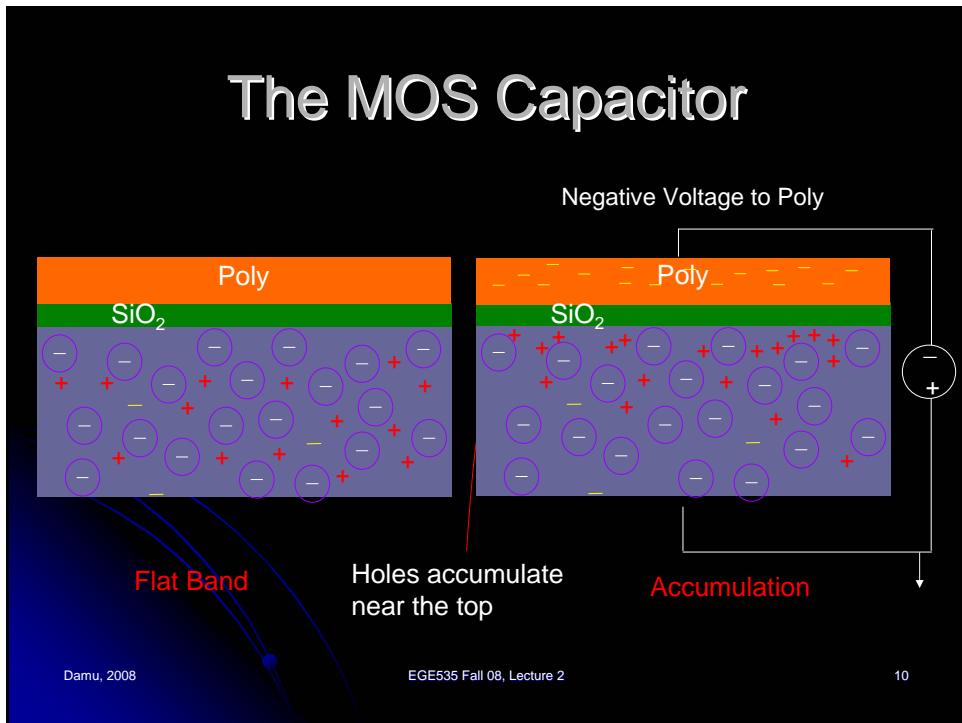
NMOS Transistor



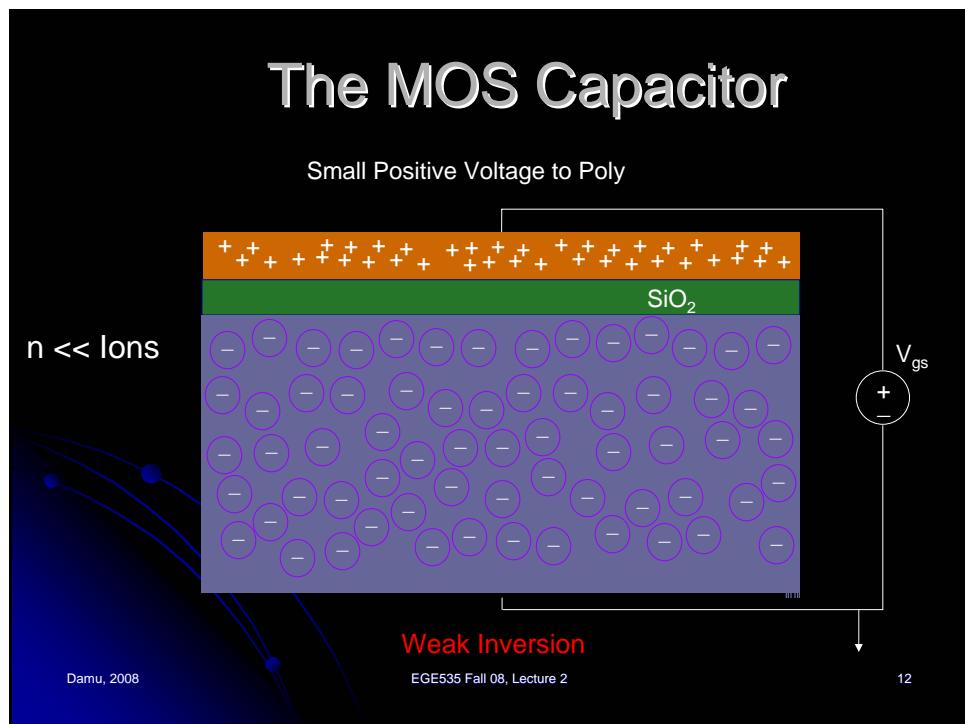
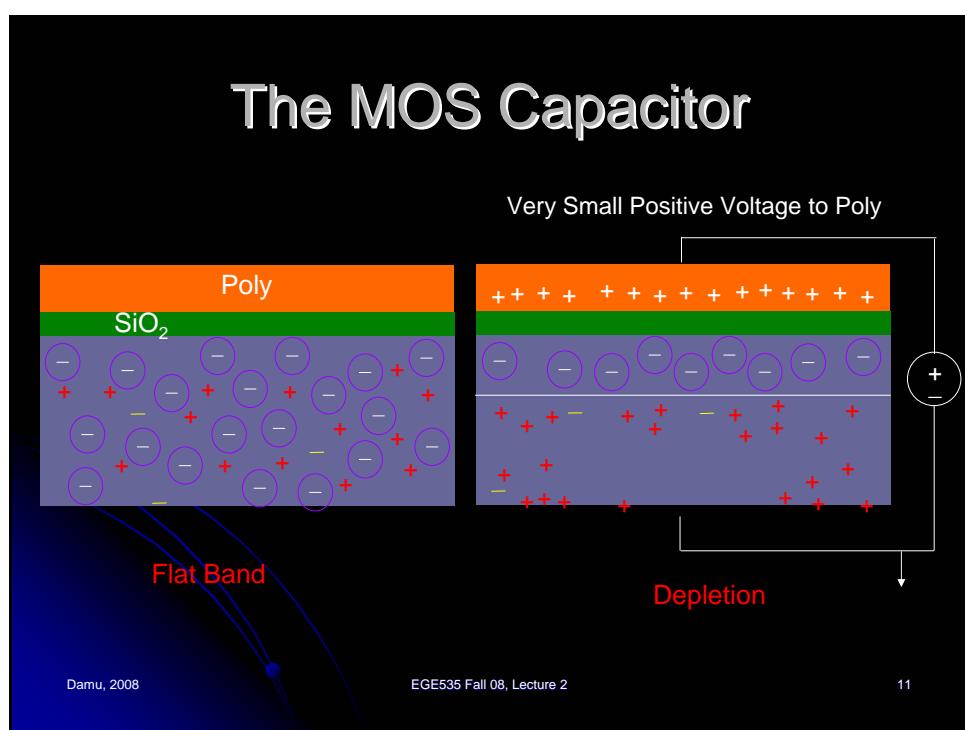
Capacitor Charging



The MOS Capacitor



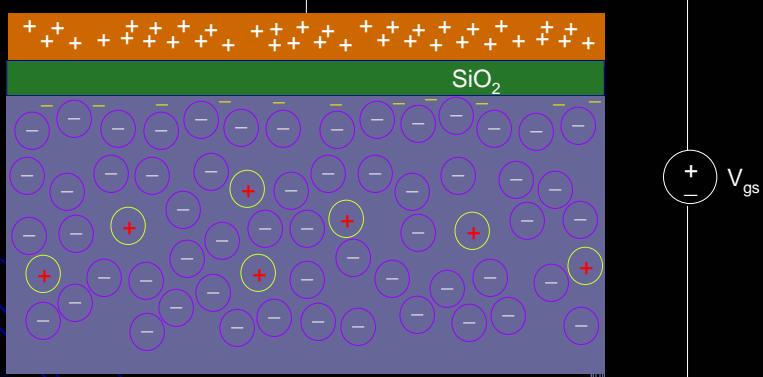
The MOS Capacitor



Threshold Voltage V_{th}

More Positive Voltage to Poly $V_{gs} = V_{th}$

$n \approx \text{ions}$



Moderate Inversion

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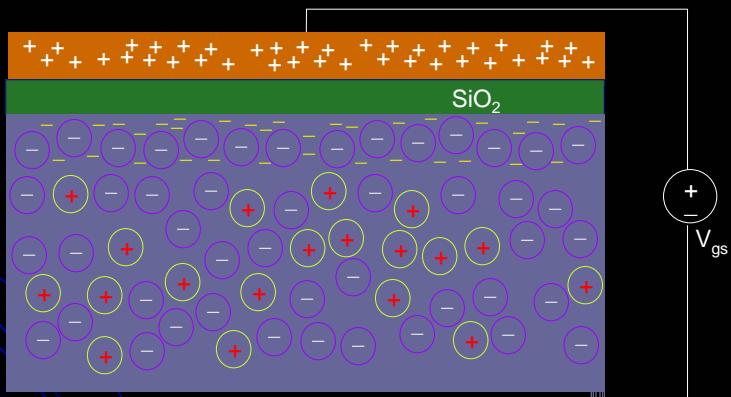
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Strong Inversion

Much More Positive Voltage $V_{gs} \gg V_{th}$

$n \gg \text{ions}$



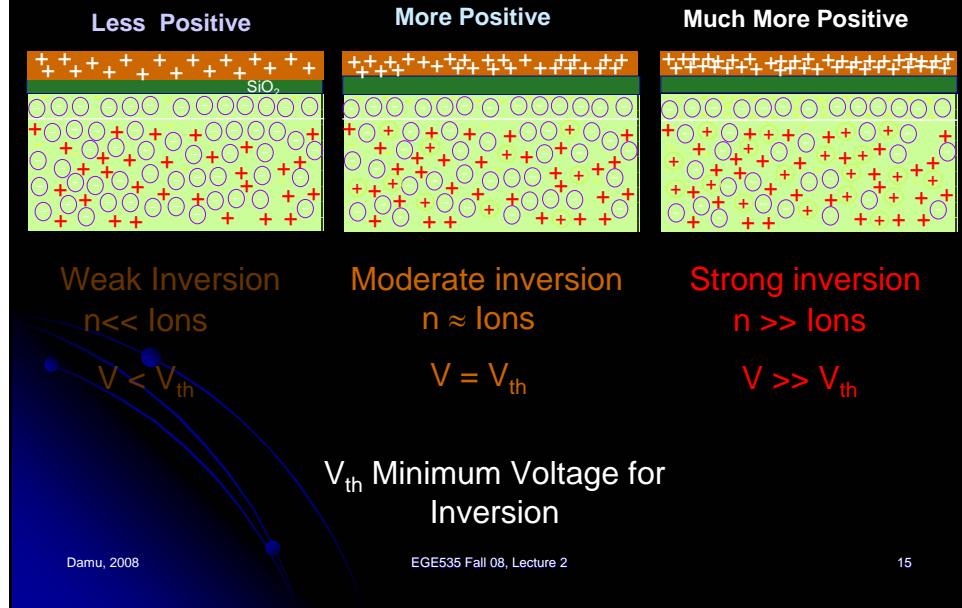
Strong Inversion

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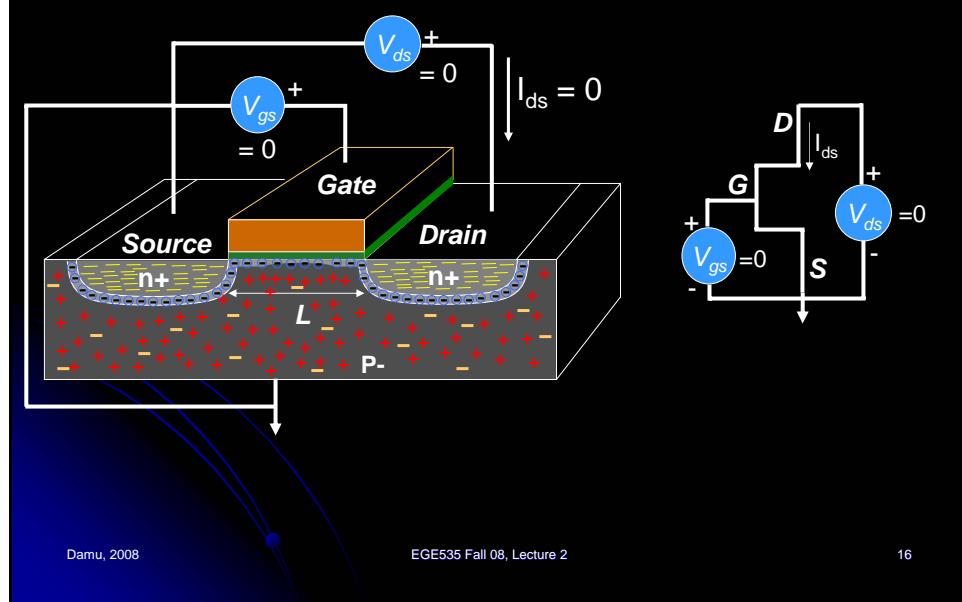
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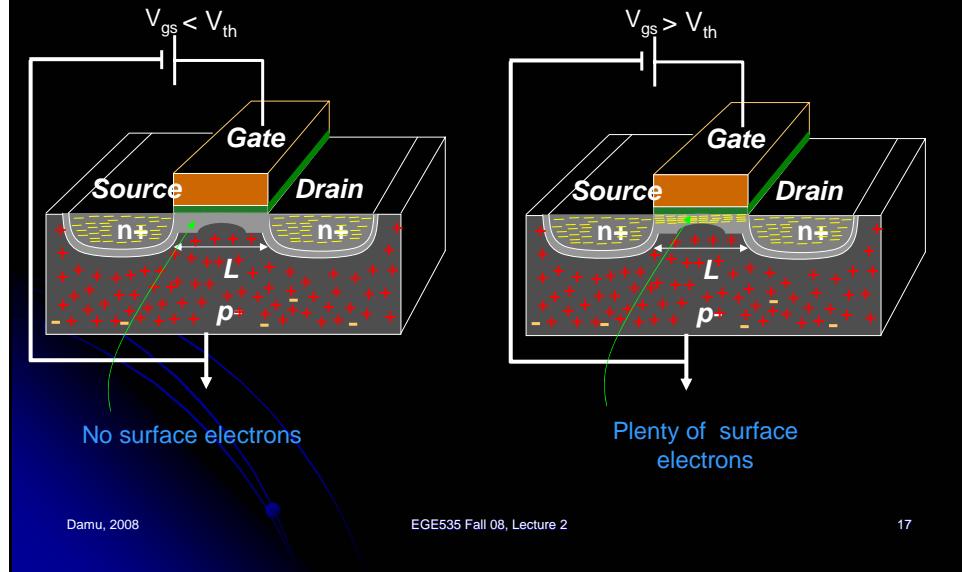
Threshold Voltage V_{th}



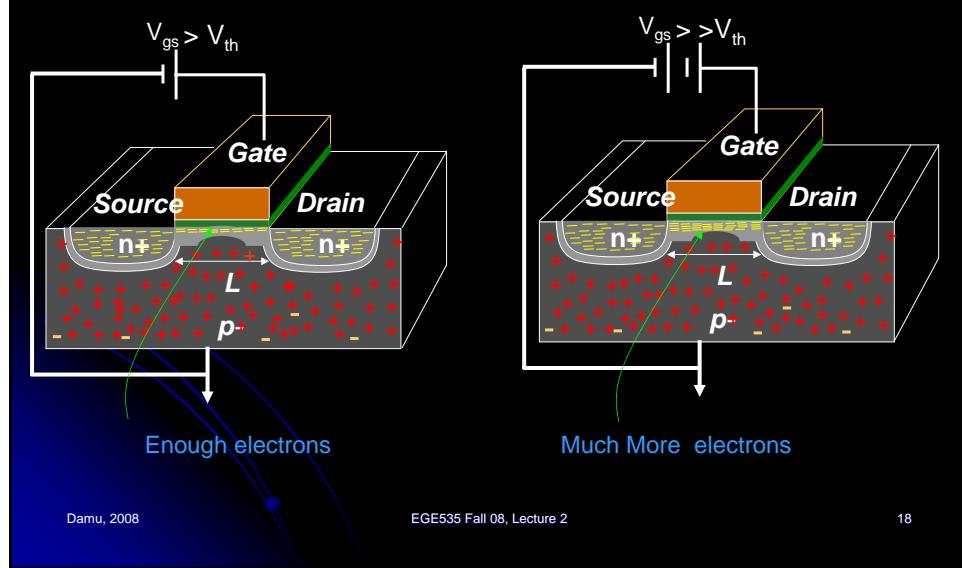
Cutoff: $I_{ds} = 0$



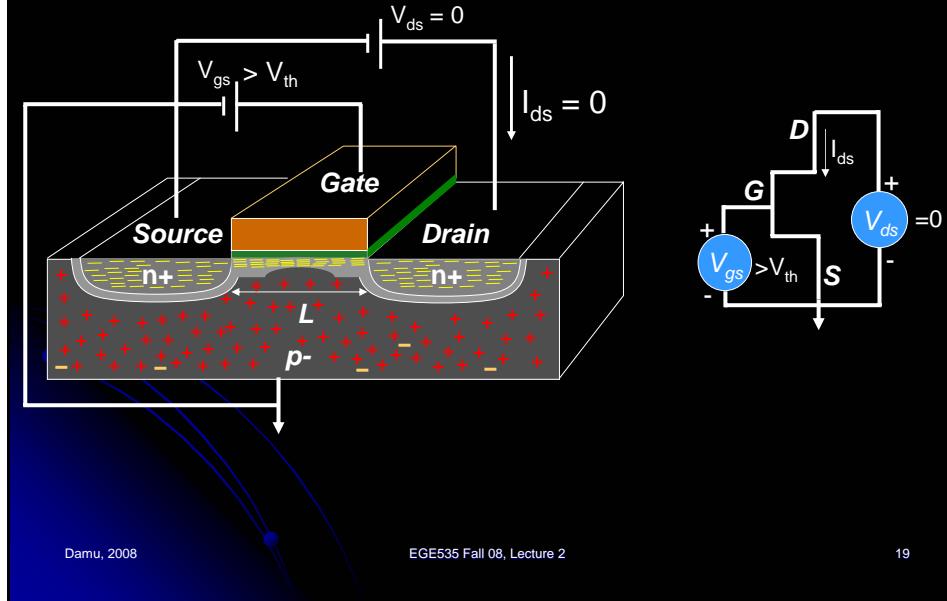
First Approximation: Threshold Voltage



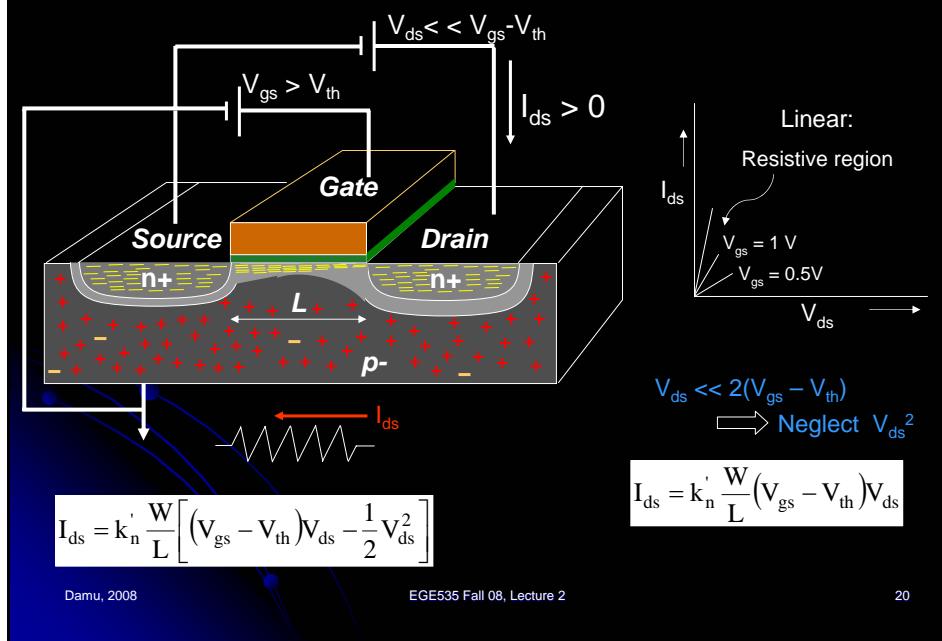
Surface Charge with V_{gs}



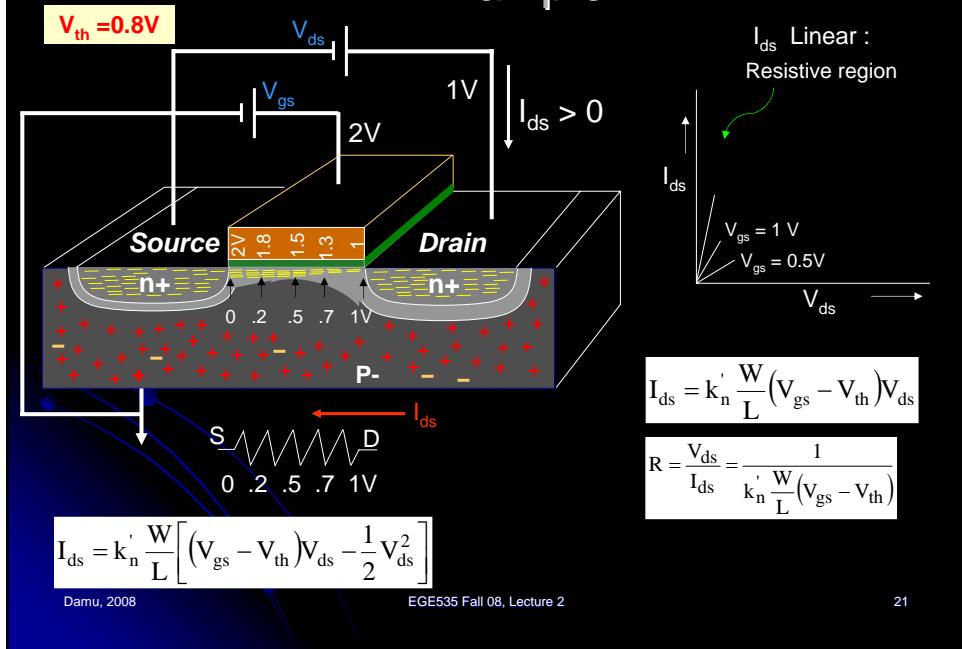
Cutoff: $I_{ds} = 0$



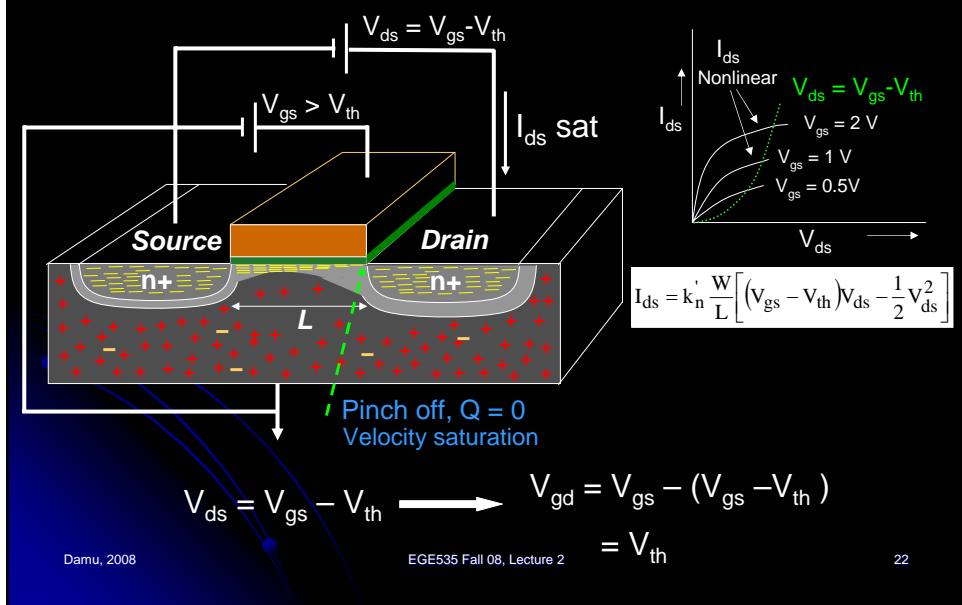
Linear: I_{ds} increases with V_{ds}

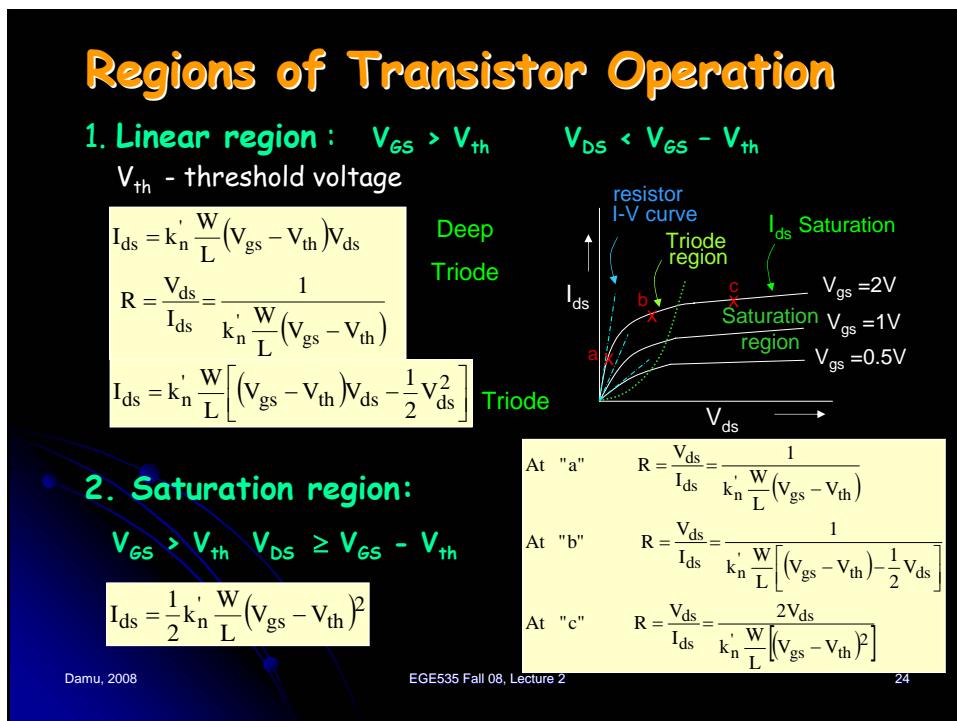
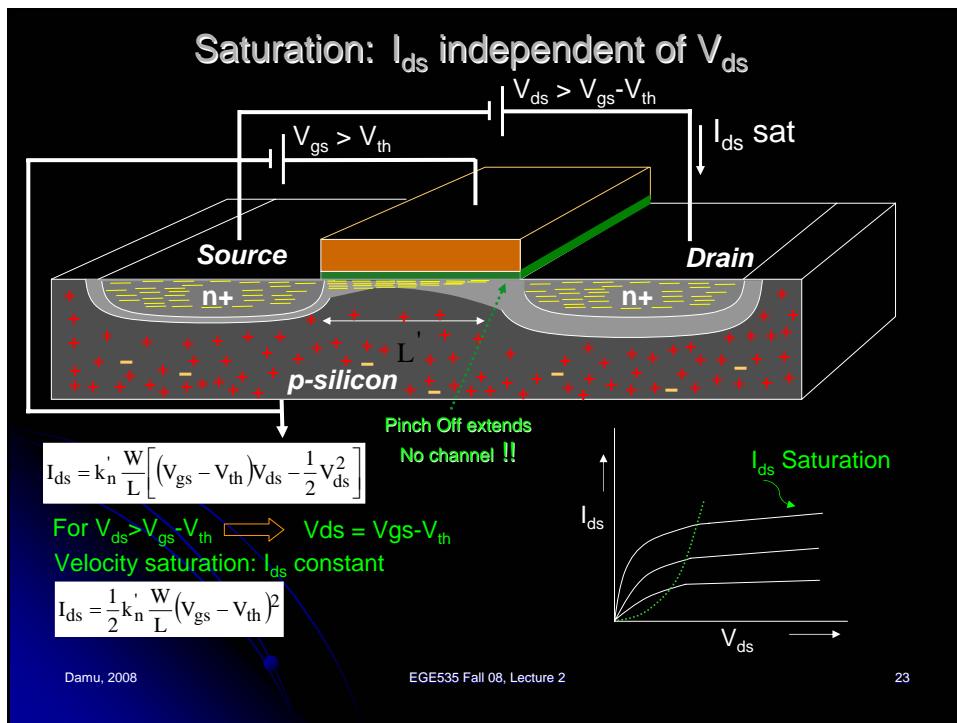


Example



Pinch Off: $V_{ds} = V_{gs} - V_{th}$





Current Equation

$$I_{ds} = k_n \frac{W}{L} \left[(V_{gs} - V_{th}) V_{ds} - \frac{1}{2} V_{ds}^2 \right] \quad \frac{W}{L} - \text{Aspect ratio}$$

$k_n = \mu_n C_{ox}$ - Process Transconductance

μ_n - Mobility of surface electrons

C_{ox} - Gate Capacitance / Unit area

$$C_{ox} = \frac{\epsilon}{t_{ox}}, \quad \epsilon = \epsilon_0 \epsilon_r \quad \text{Permitivity of SiO}_2$$

ϵ_r Relative permitivity = 3.9

$$\epsilon_0 \text{ Permitivity of freespace} = 8.854 \times 10^{-14} \text{ F/cm}$$

t_{ox} Gate Oxide thickness $\approx 200^0 = 20\text{nm}$

$$\beta_n = k_n \frac{W}{L} - \text{Device transconductance}$$

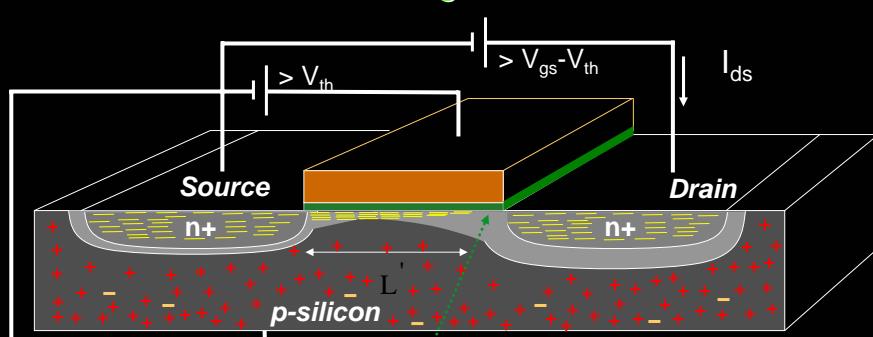
$$C_{ox} = 1.725 \text{ fF}/\mu\text{m}^2$$

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Channel Length Modulation

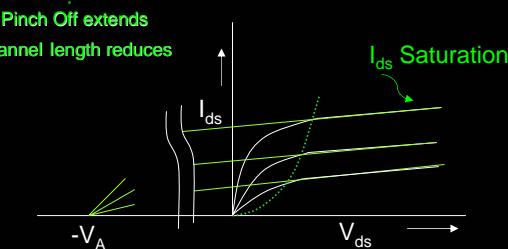


$$I_{ds} = \frac{1}{2} k_n \frac{W}{L} (V_{gs} - V_{th})^2$$

$$I_{ds} = \frac{1}{2} k_n \frac{W}{L} (V_{gs} - V_{th})^2 \left(1 + \frac{V_{ds}}{V_a} \right)$$

$$I_{ds} = \frac{1}{2} k_n \frac{W}{L} (V_{gs} - V_{th})^2 (1 + \lambda V_{ds})$$

$$0.005 \leq \lambda \leq 0.02 \text{ V}^{-1}$$

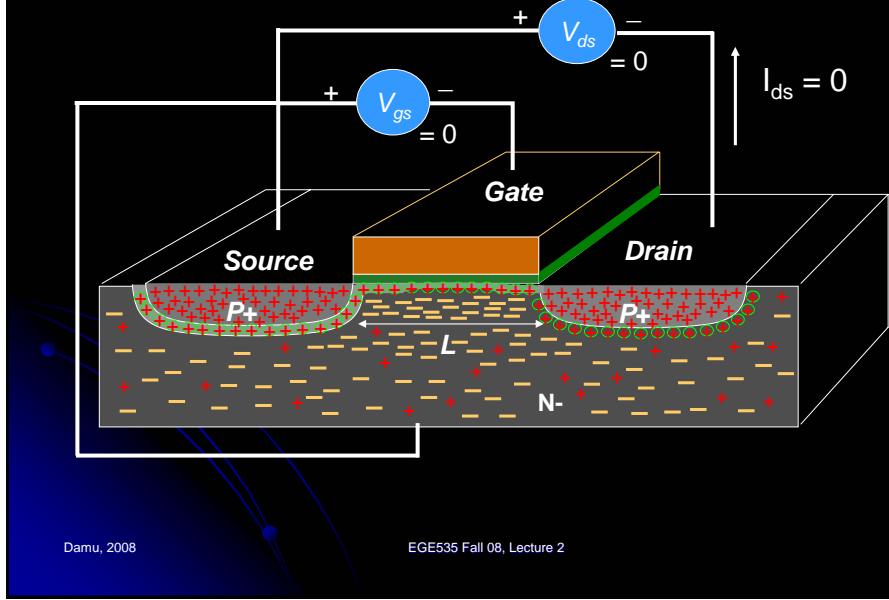


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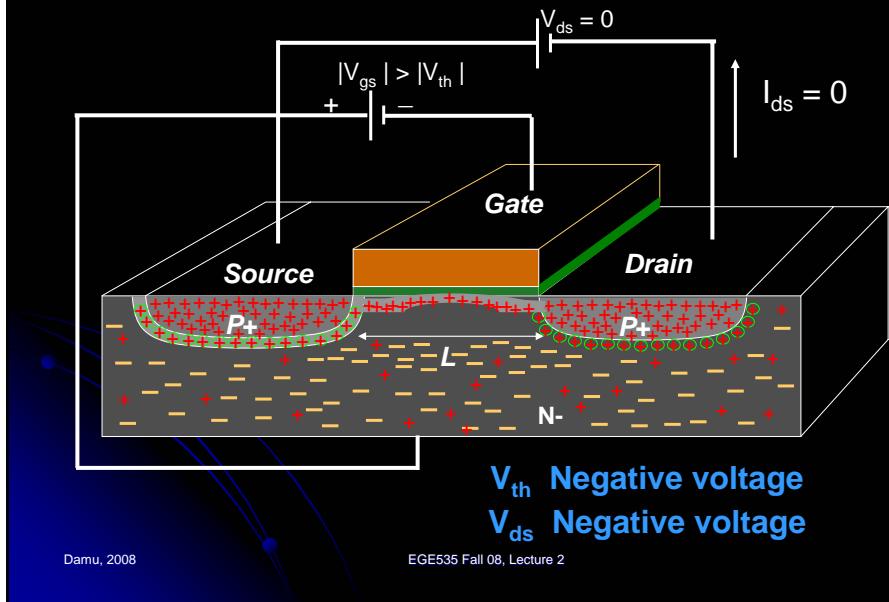
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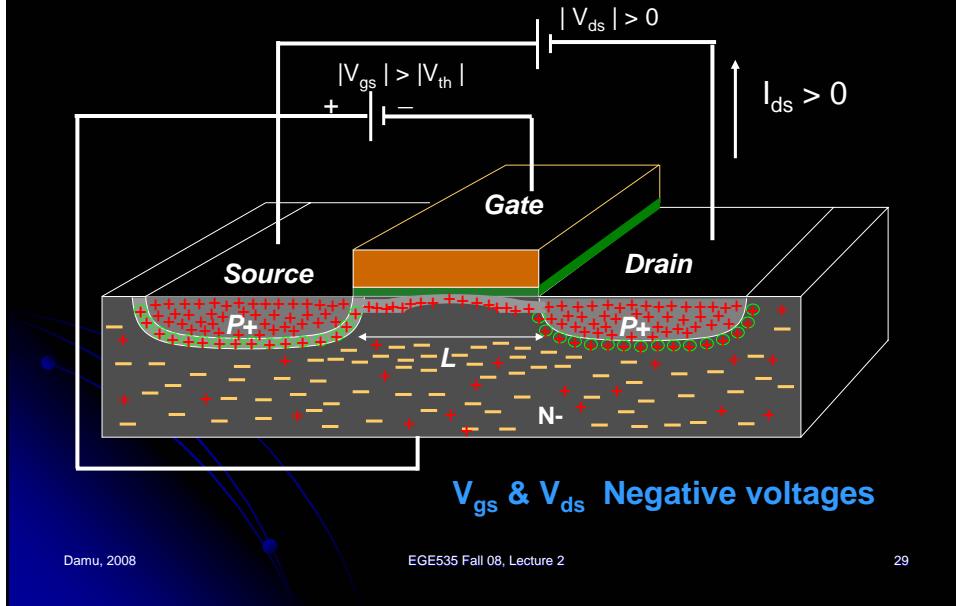
PMOSFET



PMOSFET: No current



PMOSFET: Current flow



PMOS Transistor

1. **Linear region :** $|V_{gs}| > |V_{th}|$

V_{th} - threshold voltage (Min for inversion layer)

$$I_{ds} = k_n \frac{W}{L} (V_{gs} - V_{th}) V_{ds} \quad |V_{ds}| \ll |V_{gs} - V_{th}| \text{ Deep Triode}$$

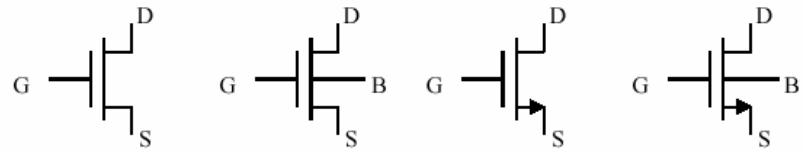
$$I_{ds} = k_n \frac{W}{L} \left[(V_{gs} - V_{th}) V_{ds} - \frac{1}{2} V_{ds}^2 \right] \quad |V_{ds}| < |V_{gs} - V_{th}| \text{ Triode}$$

2. **Saturation region:** $|V_{gs}| > |V_{th}|$

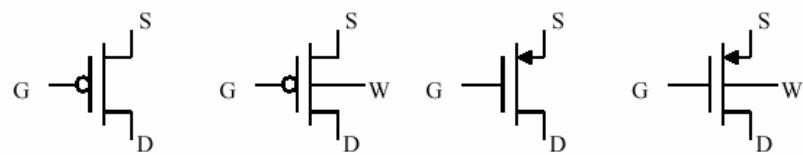
$$I_{ds} = \frac{1}{2} k_n \frac{W}{L} (V_{gs} - V_{th})^2 \quad |V_{ds}| \geq |V_{gs} - V_{th}|$$

MOSFET Symbols

*n*FET symbols



*p*FET symbols



(G = gate; S = source, D = drain; B = bulk; W = well)